



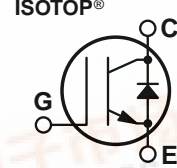
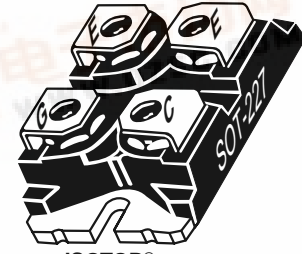
# APT40GF120JRD

1200V 60A

## Fast IGBT & FRED

The Fast IGBT™ is a new generation of high voltage power IGBTs. Using Non-Punch Through Technology the Fast IGBT™ combined with an APT free-wheeling ultraFast Recovery Epitaxial Diode (FRED) offers superior ruggedness and fast switching speed.

- Low Forward Voltage Drop
- Low Tail Current
- RBSOA and SCSOA Rated
- Ultrafast Soft Recovery Antiparallel Diode
- High Freq. Switching to 20KHz
- Ultra Low Leakage Current



### MAXIMUM RATINGS (IGBT)

All Ratings:  $T_C = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	APT40GF120JRD	UNIT
$V_{CES}$	Collector-Emitter Voltage	1200	Volts
$V_{CGR}$	Collector-Gate Voltage ( $R_{GE} = 20K\Omega$ )	1200	
$V_{GE}$	Gate-Emitter Voltage	$\pm 20$	
$I_{C1}$	Continuous Collector Current @ $T_C = 25^\circ\text{C}$	60	Amps
$I_{C2}$	Continuous Collector Current @ $T_C = 90^\circ\text{C}$	40	
$I_{CM1}$	Pulsed Collector Current <sup>①</sup> @ $T_C = 25^\circ\text{C}$	120	
$I_{CM2}$	Pulsed Collector Current <sup>①</sup> @ $T_C = 90^\circ\text{C}$	80	
$P_D$	Total Power Dissipation	390	Watts
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to 150	$^\circ\text{C}$
$T_L$	Max. Lead Temp. for Soldering: 0.063" from Case for 10 Sec.	300	

### STATIC ELECTRICAL CHARACTERISTICS (IGBT)

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
$BV_{CES}$	Collector-Emitter Breakdown Voltage ( $V_{GE} = 0V, I_C = 0.8mA$ )	1200			Volts
$V_{GE(TH)}$	Gate Threshold Voltage ( $V_{CE} = V_{GE}, I_C = 700\mu A, T_j = 25^\circ\text{C}$ )	4.5	5.5	6.5	
$V_{CE(ON)}$	Collector-Emitter On Voltage ( $V_{GE} = 15V, I_C = 40A, T_j = 25^\circ\text{C}$ )		2.9	3.4	
	Collector-Emitter On Voltage ( $V_{GE} = 15V, I_C = 40A, T_j = 125^\circ\text{C}$ )		3.5	4.1	
$I_{CES}$	Collector Cut-off Current ( $V_{CE} = V_{CES}, V_{GE} = 0V, T_j = 25^\circ\text{C}$ ) <sup>②</sup>			0.8	mA
	Collector Cut-off Current ( $V_{CE} = V_{CES}, V_{GE} = 0V, T_j = 125^\circ\text{C}$ ) <sup>②</sup>			TBD	
$I_{GES}$	Gate-Emitter Leakage Current ( $V_{GE} = \pm 20V, V_{CE} = 0V$ )			$\pm 100$	nA

**CAUTION:** These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

APT Website - <http://www.advancedpower.com>

**DYNAMIC CHARACTERISTICS (IGBT)**
**APT40GF120JRD**

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
$C_{ies}$	Input Capacitance	<b>Capacitance</b> $V_{GE} = 0V$ $V_{CE} = 25V$ $f = 1 \text{ MHz}$		3500	4700	pF
$C_{oes}$	Output Capacitance			490	700	
$C_{res}$	Reverse Transfer Capacitance			230	345	
$Q_g$	Total Gate Charge <sup>③</sup>	<b>Gate Charge</b> $V_{GE} = 15V$ $V_{CC} = 0.5V_{CES}$ $I_C = I_{C2}$		320		nC
$Q_{ge}$	Gate-Emitter Charge			30		
$Q_{gc}$	Gate-Collector ("Miller") Charge			200		
$t_{d(on)}$	Turn-on Delay Time	<b>Resistive Switching (25°C)</b> $V_{GE} = 15V$ $V_{CC} = 0.8V_{CES}$ $I_C = I_{C2}$ $R_G = 5\Omega$		35		ns
$t_r$	Rise Time			130		
$t_{d(off)}$	Turn-off Delay Time			215		
$t_f$	Fall Time			145		
$t_{d(on)}$	Turn-on Delay Time	<b>Inductive Switching (150°C)</b> $V_{CLAMP(Peak)} = 0.66V_{CES}$ $V_{GE} = 15V$ $I_C = I_{C2}$ $R_G = 5\Omega$ $T_J = +150^\circ C$		35		ns
$t_r$	Rise Time			90		
$t_{d(off)}$	Turn-off Delay Time			400		
$t_f$	Fall Time			140		
$E_{on}$	Turn-on Switching Energy <sup>④</sup>	$R_G = 5\Omega$ $T_J = +150^\circ C$		4.5		mJ
$E_{off}$	Turn-off Switching Energy			5.0		
$E_{ts}$	Total Switching Losses <sup>④</sup>			9.5		
$t_{d(on)}$	Turn-on Delay Time	<b>Inductive Switching (25°C)</b> $V_{CLAMP(Peak)} = 0.66V_{CES}$ $V_{GE} = 15V$ $I_C = I_{C2}$ $R_G = 5\Omega$ $T_J = +25^\circ C$		35		ns
$t_r$	Rise Time			100		
$t_{d(off)}$	Turn-off Delay Time			340		
$t_f$	Fall Time			105		
$E_{ts}$	Total Switching Losses <sup>④</sup>			8.0		mJ
$g_{fe}$	Forward Transconductance	$V_{CE} = 20V, I_C = I_{C2}$	6			S

**THERMAL AND MECHANICAL CHARACTERISTICS (IGBT and FRED)**

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case (IGBT)			0.32	°C/W
	Junction to Case (FRED)			0.66	
$R_{\theta JA}$	Junction to Ambient			20	
$W_T$	Package Weight		1.03		oz
			29.2		gm
Torque	Mounting Torque (Mounting = 8-32 or 4mm Machine and Terminals = 4mm Machine)			10	lb•in
				1.1	N•m

① Repetitive Rating; Pulse width limited by maximum junction temperature.

② Leakages include the FRED and IGBT.

③ See MIL-STD-750 Method 3471

④ Switching losses include the FRED and IGBT.

# ULTRAFAST SOFT RECOVERY PARALLEL DIODE

## MAXIMUM RATINGS (FRED)

All Ratings:  $T_C = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Characteristic / Test Conditions	APT40GF120JRD	UNIT
$V_R$	Maximum D.C. Reverse Voltage	1200	Volts
$V_{RRM}$	Maximum Peak Repetitive Reverse Voltage		
$V_{RWM}$	Maximum Working Peak Reverse Voltage		
$I_F(AV)$	Maximum Average Forward Current ( $T_C = 60^\circ\text{C}$ , Duty Cycle = 0.5)	60	Amps
$I_F(RMS)$	RMS Forward Current	100	
$I_{FSM}$	Non-Repetitive Forward Surge Current ( $T_J = 45^\circ\text{C}$ , 8.3ms)	540	

## STATIC ELECTRICAL CHARACTERISTICS (FRED)

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
$V_F$	Maximum Forward Voltage			$I_F = 60\text{A}$	2.5
				$I_F = 120\text{A}$	2.0
				$I_F = 60\text{A}, T_J = 150^\circ\text{C}$	2.0

## DYNAMIC CHARACTERISTICS (FRED)

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$t_{rr1}$	Reverse Recovery Time, $I_F = 1.0\text{A}$ , $di_F/dt = -15\text{A}/\mu\text{s}$ , $V_R = 30\text{V}$ , $T_J = 25^\circ\text{C}$		70	85	ns
$t_{rr2}$	Reverse Recovery Time		$T_J = 25^\circ\text{C}$ 70		
$t_{rr3}$	$I_F = 60\text{A}$ , $di_F/dt = -480\text{A}/\mu\text{s}$ , $V_R = 650\text{V}$		$T_J = 100^\circ\text{C}$ 130		
$t_{fr1}$	Forward Recovery Time		$T_J = 25^\circ\text{C}$ 170		
$t_{fr2}$	$I_F = 60\text{A}$ , $di_F/dt = 480\text{A}/\mu\text{s}$ , $V_R = 650\text{V}$		$T_J = 100^\circ\text{C}$ 170		
$I_{RRM1}$	Reverse Recovery Current		$T_J = 25^\circ\text{C}$ 18	30	Amps
$I_{RRM2}$	$I_F = 60\text{A}$ , $di_F/dt = -480\text{A}/\mu\text{s}$ , $V_R = 650\text{V}$		$T_J = 100^\circ\text{C}$ 29	40	
$Q_{rr1}$	Recovery Charge		$T_J = 25^\circ\text{C}$ 630		nC
$Q_{rr2}$	$I_F = 60\text{A}$ , $di_F/dt = -480\text{A}/\mu\text{s}$ , $V_R = 650\text{V}$		$T_J = 100^\circ\text{C}$ 1820		
$V_{fr1}$	Forward Recovery Voltage		$T_J = 25^\circ\text{C}$ 12		Volts
$V_{fr2}$	$I_F = 60\text{A}$ , $di_F/dt = 480\text{A}/\mu\text{s}$ , $V_R = 650\text{V}$		$T_J = 100^\circ\text{C}$ 12		
$diM/dt$	Rate of Fall of Recovery Current		$T_J = 25^\circ\text{C}$ 900		A/ $\mu\text{s}$
	$I_F = 60\text{A}$ , $di_F/dt = -480\text{A}/\mu\text{s}$ , $V_R = 650\text{V}$		$T_J = 100^\circ\text{C}$ 600		

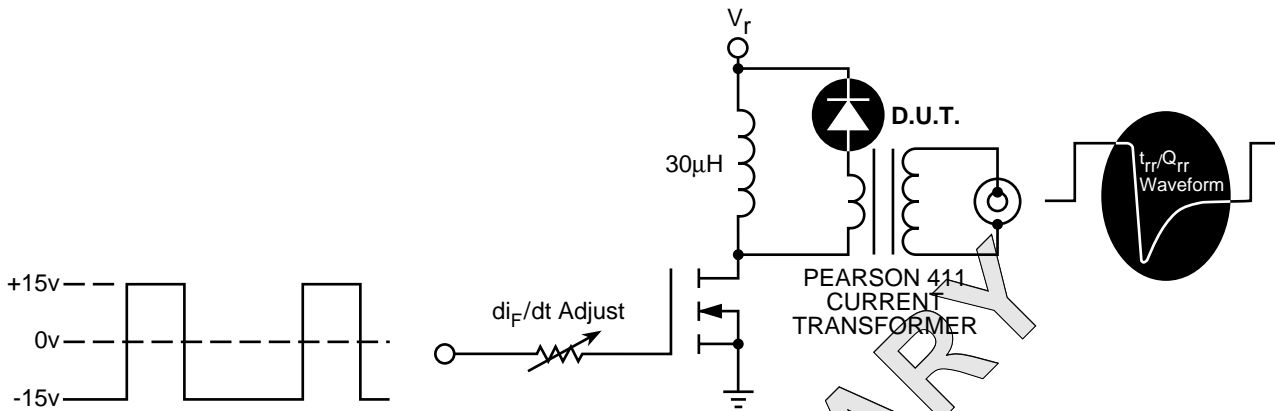
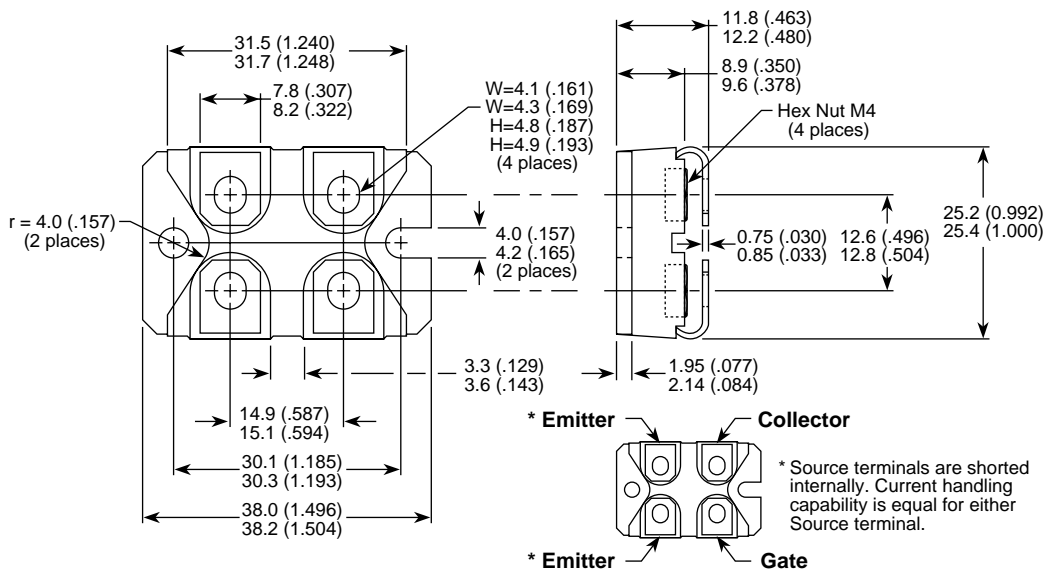


Figure 25, Diode Reverse Recovery Test Circuit and Waveforms

- 1  $I_F$  - Forward Conduction Current
  - 2  $di_F/dt$  - Current Slew Rate, Rate of Forward Current Change Through Zero Crossing.
  - 3  $I_{RRM}$  - Peak Reverse Recovery Current.
  - 4  $t_{rr}$  - Reverse Recovery Time Measured from Point of  $I_F$  Current Falling Through Zero to a Tangent Line { 6  $di_M/dt$  } Extrapolated Through Zero Defined by 0.75 and 0.50  $I_{RRM}$ .
  - 5  $Q_{rr}$  - Area Under the Curve Defined by  $I_{RRM}$  and  $t_{rr}$ .
  - 6  $di_M/dt$  - Maximum Rate of Current Change During the Trailing Portion of  $t_{rr}$ .
- $$Q_{rr} = \frac{1}{2} (t_{rr} \cdot I_{RRM})$$

SOT-227 (ISOTOP®) Package Outline



Dimensions in Millimeters and (Inches)